ABSTRACT OF THE DISCLOSURE

An image sensor module includes a substrate, a photosensitive chip, a lens holder and a lens barrel. The substrate has a upper surface and a lower surface. The photosensitive chip is arranged at the upper surface of the substrate, and electrically connected the substrate by a plurality of wires. The lens holder is formed with a penetrated hole at a central thereof, an internal thread being formed on the inner wall of the penetrate hole, the lens holder being mounted on the upper surface of the first substrate to encapsulate the photosensitive chip. The lens barrel is arranged within the penetrate hole of the lens holder and is formed with an external thread, which is screwed to the internal thread of the lens holder.

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